



FULL 50-60Hz RECTIFICATION BRIDGE

PRELIMINARY DATASHEET

MAIN PRODUCT CHARACTERISTICS

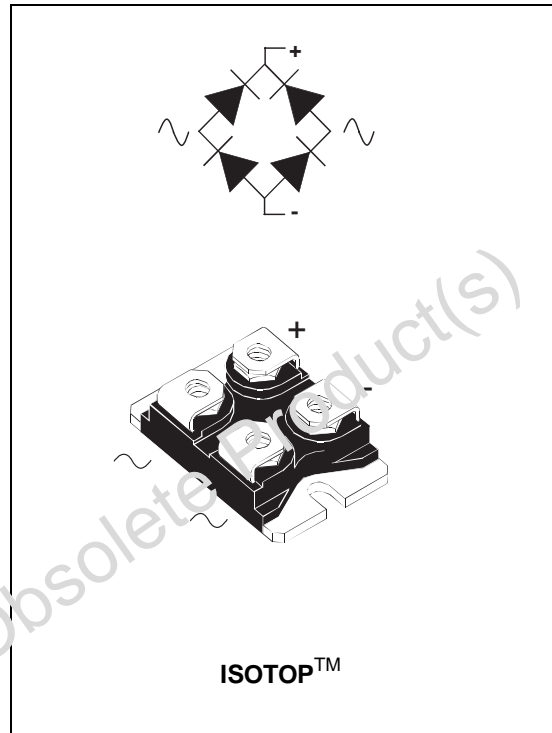
$I_{F(AV)}$	35 A
V_{RRM}	1000 V
$T_j(\text{max})$	150 °C
$V_F(\text{max})$	1.30 V

FEATURES AND BENEFITS

- COMPACT ISOTOP DESIGN COMPATIBLE WITH FAST DIODES AND TRANSISTORS.
- EXCELLENT THERMAL TRANSFER BETWEEN JUNCTION AND HEATSINK
- UL PENDING

DESCRIPTION

The Bridges series from ST Microelectronics has been designed to allow a better standardization of packages on boards principally designed with ISOTOP packages. The insulated package of the bridge will be able to sit on heatsink with other components. Single phase and 3-phase high power SMPS, UPS, MOTOR DRIVES and WELDING equipment will primarily find advantage in these industry package products.



ABSOLUTE RATINGS AND ELECTRICAL CHARACTERISTICS (per diode unless specified)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	1000	V
V_{REM}	Non repetitive peak reverse voltage	1000	V
$I_{F(AV)} \text{ total}$	Average forward current $T_c = 80^\circ\text{C}$ sinusoidal	35	A
I_{FSM}	Surge non repetitive forward current 50Hz JEDEC method	300	A
$I^2.t$	Fusing	660	$\text{A}^2.\text{s}$
T_{stg}	Storage temperature range	- 55 to + 150	°C
T_j	Maximum operating junction temperature	150	°C
$P_{max \text{ total}}$	Total power dissipation	50	W

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BF3510TV

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth (j-c)	Junction to case	total	0.5	°C/W

ELECTRICAL CHARACTERISTICS (Per diode) STATIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
I _R *	Reverse leakage current	V _R = 0.8 V _{RRM} δ < 2% tp = 5ms	T _j = 25°C			10	μA
			T _j = 125°C			0.2	mA
V _F **	Forward voltage drop	I _F = 35 A δ < 2% tp = 380μs	T _j = 25°C			1.4	V
			T _j = 125°C			1.3	V

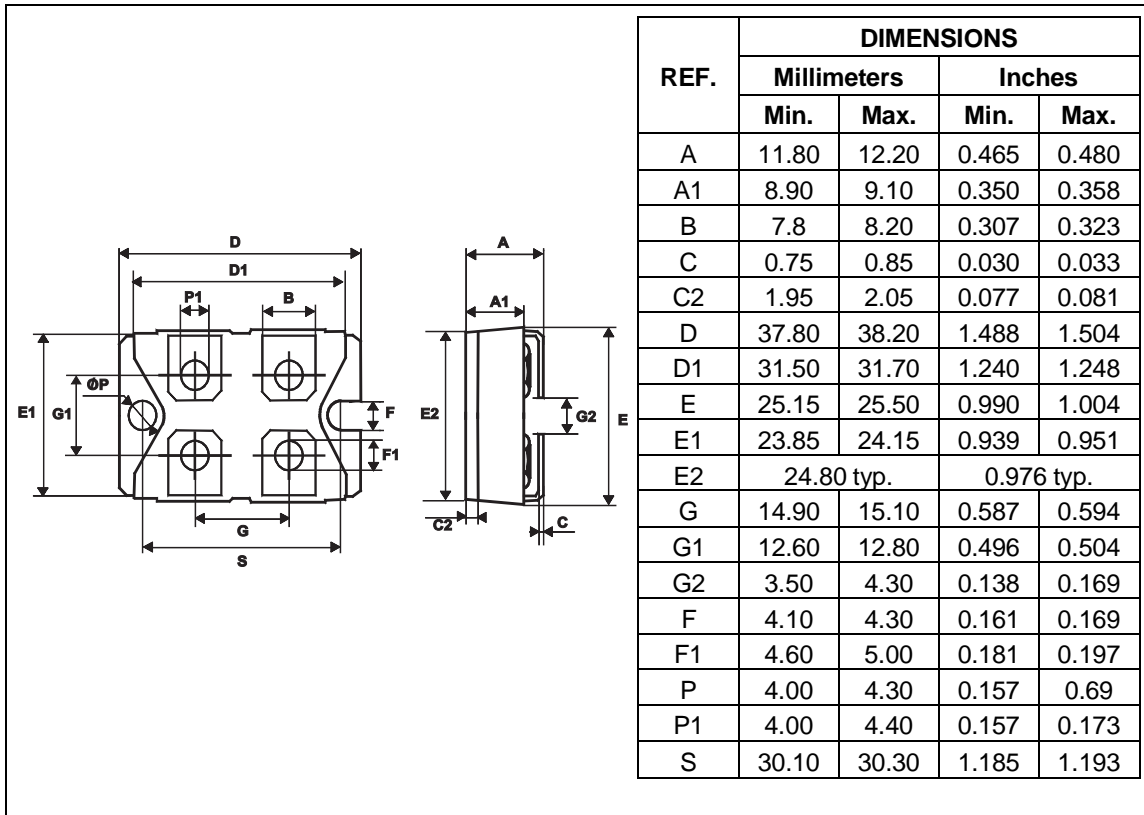
Pulse test : * tp = 5 ms, duty cycle < 2 %

** tp = 380 μs, duty cycle < 2 %

For one diode: $P_{cond} = 1.02 \times I_{F(AV)} + 0.008 \times I_{F(RMS)}^2$

$T_j = P_{cond} \times 4 \times R_{th(j-c)} + T_c$

PACKAGE MECHANICAL DATA
ISOTOP (Plastic)



Cooling method : by conduction (C)
Electrical isolation : 2500V_(RMS)

Capacitance : < 45 pF
Inductance : < 5 nH

- Recommended torque value : 1.3 N.m (MAX 1.5 N.m) for the 6 x M4 screws. (2 x M4 screws recommended for mounting the package on the heatsink and the 4 screws given with the screw version).
- The screws supplied with the package are adapted for mounting on a board (or other types of terminals) with a thickness of 0.6 mm min and 2.2 mm max.

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
BF3510TV	BF3510TV	ISOTOP	27g without screws	10	Tube

■ Epoxy meets UL94,V0

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